

XP-002259511

AN - 2003-136590 [13]

AP - KR20000085074 20001229

CPY - CHEI-N

DC - A26 A85 L03 U14

FS - CPI;EPI

IC - C08G59/48

IN - KIM Y H; LEE M Y; OH J M

MC - A08-S02 A09-A02A A10-D L03-D01D3 L03-G05B

- U14-K01A1A

PA - (CHEI-N) CHEIL IND INC

PN - KR2002055837 A 20020710 DW200313 C08G59/48 001pp

PR - KR20000085074 20001229

XA - C2003-034671

XIC - C08G-059/48

AB - KR2002055837 NOVELTY - Provided is a polyamic acid resin composition which has improved smoothness, printability, and liquid crystal orientation and is cured at low temperature.

- DETAILED DESCRIPTION - The polyamic acid resin composition comprises 2-40 wt% of polyamic acid prepared by solution polymerizing diamine and tetracarboxylic acid dihydride; and 60-98 wt% of solvent represented by formula 1 (wherein R1 is an alkyl group of C1-C10 comprising at least one hydroxyl group, and R2 is an alkyl group of C1-C10, which may be substituted with at least one of hydroxyl group and ketone group. The solvent of formula 1 is 3-acetyl-1-propanol, 4-hydroxy-4-methyl-2-pentanone, 3-hydroxy-3-methyl-2-butanone, or 1-hydroxy-2-butanone.

- (Dwg.1/10)

IW - POLYAMIDEACID ACID RESIN COMPOSITION

IKW - POLYAMIDEACID ACID RESIN COMPOSITION

INW - KIM Y H; LEE M Y; OH J M

NC - 001

OPD - 2000-12-29

ORD - 2002-07-10

PAW - (CHEI-N) CHEIL IND INC

TI - Polyamic acid resin composition